

REMARKS

The following remarks are responsive to the office action of March 12, 2003, and the interview of June 12, 2003. Reconsideration of the application is respectfully requested.

The Examiner has rejected claims 12-18, 20, 22 and 23 under 35 USC 102(a) as being unpatentable over Hayward, US Patent No 5,281,481, in view of Fukatani, US Patent No 4,537,299. The Examiner acknowledges that Hayward fails to teach that the friction plates may be sintered, and finds that Fukatani teaches this limitation. The Examiner has rejected claims 19 and 21 under 35 USC 103(a) over Hayward, in view of Fukatani, in further view of Watremez, US Patent No 5,629,101. The Examiner finds that Hayward does not teach an aluminum substrate, and asserts that Watremez teaches an aluminum substrate.

Applicant expresses appreciation to the Examiner for conducting the interview of June 12, 2003. In the interview, Applicant and Examiner discussed the importance of bonding sintered plates to a metal core having a low melting temperature, such as Aluminum. For example, Aluminum has a melting temperature of approximately 1220 degrees Fahrenheit, and the bonding temperature of sintered plates is at least approximately 1380 degrees Fahrenheit.

The Examiner stated that claim 12 and claim 20 would distinguish over the cited prior art and, subject to an updated search, be patentable over the prior art if (1) the claims were amended to recite the melting temperature of

the metal is approximately 1220 degrees Fahrenheit, and (2) a declaration was provided which disclosed the bonding temperature of sintered plates and the melting temperature of Aluminum. Accordingly, Applicant has amended independent claims 12 and 20 to include the discussed limitation and provided the requested declaration.

Accordingly, Applicant asserts that claims 12 and 20 are patentable over the prior art, and claims 13-19, depending from claim 12, and claims 21-23, depending from claims 20, are patentable therewith. A notice of allowance is respectfully requested.

Enclosed, please find a check in the amount of \$55.00 to cover a one-month extension of time. Please charge any additional fees to Deposit Account No. 06-0515.

Respectfully submitted,

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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VERSION WITH MARKINGS

Siri:

In response to the Office Action of March 12, 2003, and the interview of June 12, 2003, the application has been amended as follows:

In the Claims:

Claims 12 and 20 have been amended as follows:

12. (Amended) An adhesive bonded sintered plate comprising:

- a top sintered layer;
 - a bottom sintered layer;
 - a top adhesive layer;
 - a bottom adhesive layer;
 - a metal core layer having a melting temperature not greater than substantially 1220 degrees

Fahrenheit;
wherein said top sintered layer is attached to
said metal core layer using said top adhesive layer.

and said bottom sintered layer is attached to said metal core using said bottom adhesive layer.

20. (Amended) An adhesive boned sintered plate comprising:

- [-] a top sintered layer;
- [-] a bottom sintered layer;
- [-] a top adhesive layer;
- [-] a bottom adhesive layer;
- [-] a metal core layer having a melting temperature not greater than substantially 1220 degrees
Fahrenheit;

wherein said top sintered layer is attached to said metal core layer using said top adhesive layer and said bottom sintered layer is attached to said metal core using said bottom adhesive layer;

wherein each of said top sintered layer [is attached to said metal core layer] and said bottom sintered layer [is] being attached to said metal core layer at a bonding temperature, bonding pressure, and a bonding time, wherein:

- d. said bonding pressure is in the range of 25 to 1000 psi;
- e. said bonding temperature is in the range of 375 degrees Fahrenheit to 475 degrees Fahrenheit; and
- f. said bonding time is at least 30 seconds.